

## Training and usage policy

- Controlled access tool.
- Request needs to be submitted by Thursday afternoon 2 pm, which will be scheduled to be executed on Friday. Maximum number of 5 requests will be served every week (one deposition takes 4-4.5 hour) on first cum first serve basis. The additional requests will be kept in a queue.
- Requests will not be migrated to other days in case the tool is down in those days.
- Slots are not transferrable
- Materials that will be deposited: Ti, Al, Ni and Au
- Maximum thicknesses allowed for each of the materials: Ti – 100 nm, Al – 50 nm, Ni – 100 nm, Au – 100 nm. Al thicker than 50 nm/run is not deposited. Multiple depositions of Al are not allowed for the same sample. It is currently heating up the chamber. (Solution is being worked out)
- The user to get the material approved from CEN fund or other resources and brings it along with him or deposits it with the operator after the process is approved.
- Any semiconductor substrate is allowed.
- Sample history for each sample will be thoroughly checked. Any incomplete or ambiguous declaration will delay the process.
- The deposition quality will be critically monitored through pre-calibrated Ohmic contact recipes. Any significant deviation will lead to reviewing this usage policy.